



Material Content Data Sheet



Halogen-Free

Sales Product Name	IPG20N06S2L-50A	Issued	13. May 2021
MA#	MA002213658		
Package	PG-TDSON-8-10	Weight*	99.60 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip_1	inorganic material	silicon	7440-21-3	1.164	1.17	1.17	11686	11686
chip_2	inorganic material	silicon	7440-21-3	1.164	1.17	1.17	11686	11686
leadframe	inorganic material	phosphorus	7723-14-0	0.013	0.01		132	
	non noble metal	iron	7439-89-6	0.044	0.04		439	
	non noble metal	copper	7440-50-8	43.681	43.86	43.91	438589	439160
wire	non noble metal	aluminium	7429-90-5	0.833	0.84	0.84	8363	8363
encapsulation	organic material	carbon black	1333-86-4	0.091	0.09		909	
	plastics	epoxy resin	-	6.425	6.45		64516	
	inorganic material	silicondioxide	60676-86-0	38.734	38.89	45.43	388912	454337
leadfinish	non noble metal	tin	7440-31-5	1.396	1.40	1.40	14021	14021
plating	inorganic material	phosphorus	7723-14-0	0.001			14	
	non noble metal	nickel	7440-02-0	0.603	0.61	0.61	6055	6069
solder	non noble metal	tin	7440-31-5	0.055	0.06		551	
	noble metal	silver	7440-22-4	0.069	0.07		689	
	non noble metal	lead	7439-92-1	2.620	2.63	2.76	26305	27545
heatspreader	inorganic material	phosphorus	7723-14-0	0.001			8	
	non noble metal	iron	7439-89-6	0.003			27	
	non noble metal	copper	7440-50-8	2.699	2.71	2.71	27098	27133
*deviation	< 10%	Sum in total:				100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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